PROCESS FOR TREATING A STRUCTURE

ABSTRACT

The invention relates to a process for treating a structure, the structure comprising, from its back side to its front side, a carrier substrate (4), an insulating layer (3) and a useful layer (2), the useful layer (2) having a free surface (S), the structure being placed in an atmosphere containing chemical species (6), the chemical species (6) being capable of reacting chemically with the useful layer (2); this treatment process is noteworthy in that the useful layer (2) is heated by a pulsed laser beam (8), the beam (8) sweeping the free surface (S), the wavelength of the beam (8) differing by at most plus or minus 15 nm from a central wavelength, the central wavelength being chosen so that the sensitivity of the reflectivity of the structure (1) relative to the insulating layer (3) is zero.

[Figure No. 4]